

CHEMTRONICS[®]

Technical Data Sheet

TDS # SWNoClean

Soder-Wick[®] No Clean Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick[®] No Clean is designed to provide fast and safe desoldering without leaving behind harmful flux residues. Soder-Wick[®] No Clean uses pure, oxygen free copper braid and a patented flux technology to make an efficient and effective desoldering braid. Soder-Wick[®] No Clean SD is available on ESD safe bobbins for protection against damage due to static electricity.


- Requires little or no post solder cleaning
- No corrosive residues
- Halide free
- ESD Safe bobbins meet specs:
MIL-STD-1686C
MIL-HDBK-263B
Static decay provision of
MIL-B-81705C
- Minimal risk of heat and static component damage

TYPICAL APPLICATIONS

Soder-Wick[®] No Clean safely removes solder from:

- Lugs and Posts
- Micro Circuits
- Surface Mount Device Pads
- Ball Grid Array Pads

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Surface Insulation Resistance			
Bellcore TR-NWT-000078 : PASS After 96 Hours (megohms) 2×10^4 Limit			
<u>Group A</u> 4.8×10^6	<u>Group B</u> 3.8×10^6	<u>Group C</u> 4.1×10^6	
ANSI/IPC J SF-818 : PASS After 168 Hours (ohms) 1.8×10^8 Limit			
<u>1-2</u> 2.3×10^{10}	<u>2-3</u> 2.6×10^{10}	<u>3-4</u> 2.8×10^{10}	<u>4-5</u> 2.8×10^{10}
Electromigration : PASS Average Insulation Resistance (megohms)-One Decade Limit			
	<u>Initial</u>	<u>Final</u>	
Group E	3.93×10^3	1.24×10^4	
Group F	3.87×10^3	2.84×10^4	
At 10x magnification no evidence of electromigration or heavy corrosion.			
Silver Chromate Test Paper	PASS		
Copper Mirror Test	PASS		
Shelflife	2 years		
RoHS/WEEE Status			

SODER-WICK[®] NO CLEAN MEETS OR EXCEEDS:

MIL-F-14256F, Type R
DOD-STD-883E, Method 2022
Bellcore TR-NWT-000078
ANSI/IPC J SF-818

Part #	Size Inches	Color	Size Metric
1	.030"	White	.76mm
2	.060"	Yellow	1.52mm
3	.080"	Green	2.03mm
4	.110"	Blue	2.79mm
5	.145"	Brown	3.68mm
6	.210"	Red	5.33mm
BGA	-	Purple	-

AVAILABILITY

Part #	Size	Length	Part #	Size	Length
60-1-5	1	5	60-1-10	1	10
60-2-5	2	5	60-2-10	2	10
60-3-5	3	5	60-3-10	3	10
60-4-5	4	5	60-4-10	4	10
60-5-5	5	5	60-5-10	5	10
60-6-5	6	5			

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick® No Clean width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F.
- 4) Place wick on solder joint and place tip of hot iron on top of wick.
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard used portion of the wick.

TECHNICAL & APPLICATION ASSISTANCE

Chemtronics® provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

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<i>VacuPak™ Packaging</i>	Part #	Size
The VacuPak™ Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.	SW16015	1
	SW16025	2
	SW16035	3
	SW16045	4
	SW16055	5
	SW160BGA	BGA

NOTE:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. ITW Chemtronics® does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

MANUFACTURED BY:

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